OLI3539V.S2-940-A

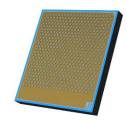
BIDOS® Core











Features:

— Chip Technology: GaAs VCSEL

- IR Laser Wavelength: 940 nm

- Optical Power Class: 10.8 W pulsed

ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Operational Mode:	Ordering Code	
	$I_F = 4 A, T_a = 25^{\circ}C$		
	$t_p = 100 \mu s, DC = 1\%$		
OLI3539V.S2-940-A	10.8 W	Q65113A3882	

Depending on the mode of operation, these devices emit highly concentrated visible and non-visible light which can be hazardous to the human eye. Products which incorporate these devices must follow the safety precautions given in the "Notes" section.



Maximum Ratings

 $T_a = 25$ °C

Parameter	Symbol		Values
Operation/Solder temperature	Ts	min.	-20 °C
$t_p = 100 \ \mu s; DC = 1 \%$		max.	100 °C
Storage temperature	T _{stg}	min.	-20 °C
		max.	110 °C
Forward current	lf	max.	7 A
Pulsed operation; T_p = 100 μ s; DC = 1%; T_S = 25°C			
Forward current	I _f	max.	3 A
Direct current operation; DC = 100%; Ts = 25°C			
Reverse Voltage	Not designed for reverse operation		
ESD withstand voltage	VESD	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)			

Note: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device.



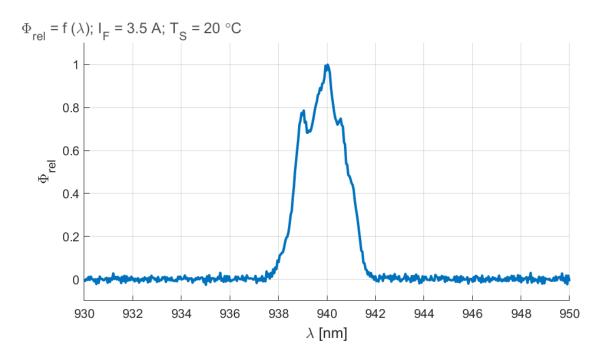
Characteristics

 $T_a = 25^{\circ}C, \; I_F = 4 \; A; \; t_p = 100 \; \mu s; \; DC = 1\%$

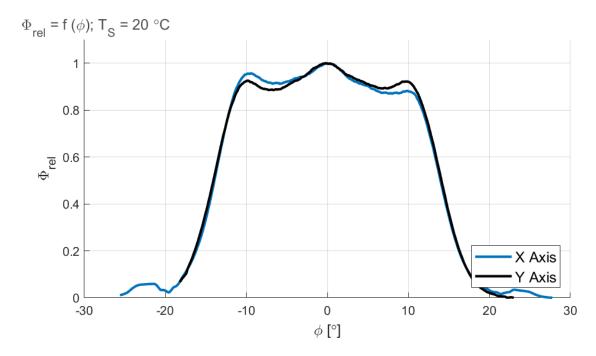
Parameter	Symbol		Values
Forward voltage	VF	typ.	5.4 V
Output power	Φ	typ.	10.8 W
Threshold current	Ith	typ.	0.5 A
Slope efficiency	SE	typ.	3.0 W / A
Power conversion efficiency	η	typ.	50 %
Peak wavelength	λ_{peak}	min.	930 nm
		typ.	940 nm
		max.	950 nm
Spectral bandwidth at FWHM (50% of Φ_{max})	λ _{FWHM}	typ.	2 nm
Temperature coefficient of wavelength	TC_λ	typ.	0.07 nm /K
Field of view at FWHM (50% of Φ_{max})		typ.	28°
	$oldsymbol{\phi}_{ ext{Y}}$	typ.	28°



Relative Spectral Emission 1)

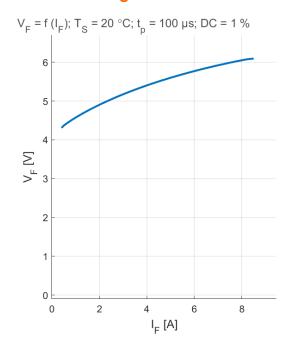


Radiation Characteristics 1)

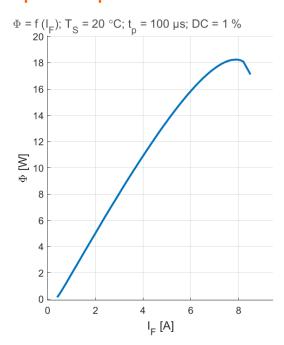




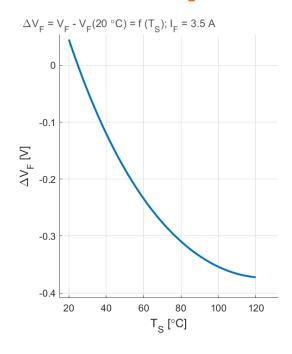
Forward Voltage 1) 2)



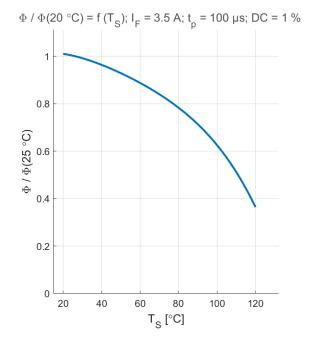
Optical Output Power 1) 2)



Relative Forward Voltage 1)

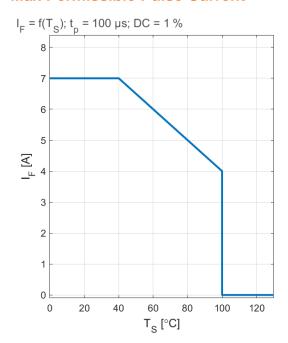


Relative Radiant Power 1)

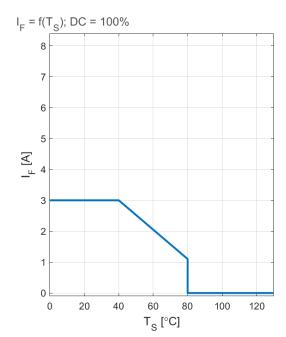




Max Permissible Pulse Current

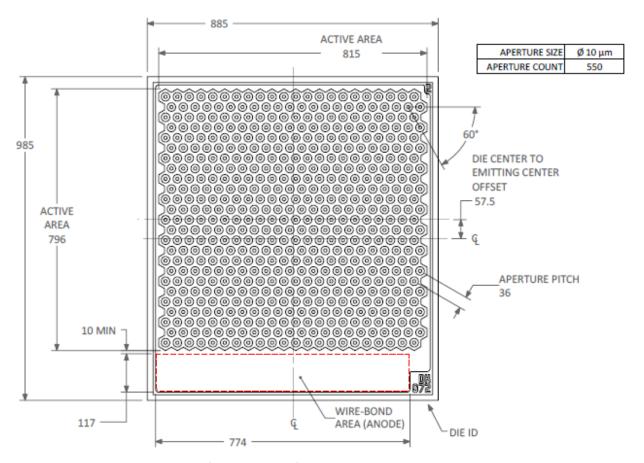


Max Permissible Current

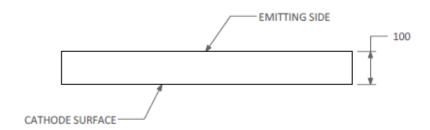




Dimension Drawings 3)



DASHED LINES (WIRE-BOND AREA) ARE NOT VISIBLE ON ACTUAL DIE





Notes

Depending on the mode of operation, these devices emit highly concentrated visible and non-visible light which can be hazardous to the human eye. Products which incorporate these devices must follow the safety precautions given in IEC 60825-1.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



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Glossary

- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Testing temperature: $T_a = 25^{\circ}C$
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.



Revision History

Version	Date	Change
1.0	Aug 24 th , 2021	Release of datasheet

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